

Amendments to the Specification where added material is shown in underlined type, deleted material is shown in ~~strikeout type~~:

Please replace paragraph [0006] with the following amended paragraph:

[0006] The present invention solves the above-identified problems of known surface mountable ~~inductors~~ inductors and transformers by providing a winding and core structure that fully occupies available space and provides for coplanar contact of both the core ends and the winding with an adjacent heat sink.

Please replace paragraph [0023] with the following amended paragraph:

[0023] The present invention will now be described in more detail with reference to the Figures. FIGS. 1-3 are several views of an inductive element 100 structured as a transformer or power choke, according to the present invention, having a surface 101 for surface mounting the inductive element on a printed circuit board (PCB) 10, where FIG. 1 is a perspective view of the inductive element mounted the surface of the PCB, FIGS. 2A and 2B are bottom and side views of inductive element 100, respectively, and FIG. 3 is a sectional view 3-3. Power choke/transformer 100 has conventional electrical operating characteristics that are a function of ~~its configuration~~ its configuration, as is well known in the field of power electronics. In addition, the mounting and use of surface-mounted transformers is similarly well known in the field and will not be repeated here.

Please replace paragraph [0036] with the following amended paragraph:

[0036] FIG. 6 is a schematic view of the present invention showing the flow of heat from the inductive element 100. Heat core 110 is provided with two conductive paths to heat sink 150 according to the present invention as follows. The novel path, indicated by the arrows labeled *Q1* does not pass through winding 120. Core 110, as well as core 400, 500, has ends 111 that protrude from elongated portion 113, which is the central portion of winding 120. The flow of heat as indicated by arrows *Q1* is thus from elongated portion 113, through ends 111, and across to the surface 142 of PCB 10 (and optionally on to a heat sink 150), where it can be transferred away from inductive element 100. The second path is the conventional path, indicated by the arrows labeled *Q2*, that passes through winding 120. Heat generated in elongated portion 113 is conducted

through winding **120**, to PCB **10** (and again optionally to a heat sink **150**). The added paths for heat transfer, and in particular path **Q1** that bypasses the winding, greatly ~~increases~~ increase the amount of heat that can be removed from inductive element **100**, thereby enabling the ability to better control the temperature of the inductive element.